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**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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*EX 6/12/03*

**In re Application of:**

Akram et al.

**Serial No.:** 09/241,177

**Filed:** February 1, 1999

**For:** HIGH DENSITY MODULARITY FOR  
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**Examiner:** C. Novacek

**Group Art Unit:** 2822

**Attorney Docket No.:** 3638US  
(98-0093.00/US)

**CERTIFICATE OF MAILING**

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May 19, 2003  
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**AMENDMENT UNDER 37 C.F.R. § 1.116**

Box AF  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

This amendment is in response to the final Office Action of March 19, 2003 whose initial period of response is set to expire on June 19, 2003.

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